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Kind regards,

Team Nexperia

IP4283CZ10 series

ESD protection for ultra high-speed interfaces

Rev. 4 — 8 April 2013

Product data sheet

1. Product profile

1.1 General description

The devices are designed to protect high-speed interfaces such as High-Definition Multimedia Interface (HDMI), DisplayPort, external Serial Advanced Technology Attachment (eSATA) and Low-Voltage Differential Signaling (LVDS) interfaces against ElectroStatic Discharge (ESD).

The devices include four high-level ESD protection diode structures for ultra high-speed signal lines. They are available in three package variants: DFN2510-10 (SOT1165-1), DFN2510A-10 (SOT1176-1) and TSSOP10 (SOT552-1).

All signal lines are protected by a special diode configuration offering ultra low line capacitance of only 0.6 pF. These diodes provide protection to downstream components from ESD voltages up to ± 8 kV contact according to IEC 61000-4-2, level 4.

1.2 Features and benefits

- System ESD protection for HDMI, DisplayPort, eSATA and LVDS
- All signal lines with integrated rail-to-rail clamping diodes for downstream ESD protection of ± 8 kV according to IEC 61000-4-2, level 4
- Matched 0.5 mm trace spacing
- Signal lines with ≤ 0.05 pF matching capacitance between signal pairs
- Line capacitance of only 0.6 pF for each channel
- Design-friendly 'pass-thru' signal routing

1.3 Applications

The devices are designed for high-speed receiver and transmitter port protection:

- TVs, monitors
- DVD recorders and players
- Notebooks, main board graphics cards and ports
- Set-top boxes and game consoles



2. Pinning information

Table 1. Pinning

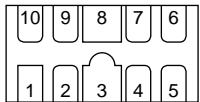
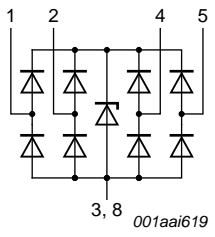
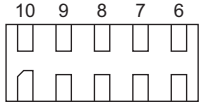
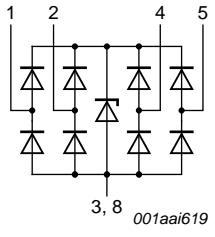
Pin	Symbol	Description	Simplified outline	Graphic symbol
IP4283CZ10-TBA (SOT1165-1)				
1	TMDS_CH1-	negative channel 1 ESD protection	 <p>Transparent top view DFN2510-10</p>	 <p>001aai619</p>
2	TMDS_CH1+	positive channel 1 ESD protection		
3	GND	ground		
4	TMDS_CH2-	negative channel 2 ESD protection		
5	TMDS_CH2+	positive channel 2 ESD protection		
6	n.c.	not connected		
7	n.c.	not connected		
8	GND	ground		
9	n.c.	not connected		
10	n.c.	not connected		
IP4283CZ10-TBR (SOT1176-1)				
1	TMDS_CH1-	negative channel 1 ESD protection	 <p>Transparent top view DFN2510A-10</p>	 <p>001aai619</p>
2	TMDS_CH1+	positive channel 1 ESD protection		
3	GND	ground		
4	TMDS_CH2-	negative channel 2 ESD protection		
5	TMDS_CH2+	positive channel 2 ESD protection		
6	n.c.	not connected		
7	n.c.	not connected		
8	GND	ground		
9	n.c.	not connected		
10	n.c.	not connected		

Table 1. Pinning ...continued

Pin	Symbol	Description	Simplified outline	Graphic symbol
IP4283CZ10-TT (SOT552-1)				
1	TMDS_CH1-	negative channel 1 ESD protection	<p style="text-align: center;">TSSOP10</p>	
2	TMDS_CH1+	positive channel 1 ESD protection		
3	GND	ground		
4	TMDS_CH2-	negative channel 2 ESD protection		
5	TMDS_CH2+	positive channel 2 ESD protection		
6	n.c.	not connected		
7	n.c.	not connected		
8	GND	ground		
9	n.c.	not connected		
10	n.c.	not connected		

3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
IP4283CZ10-TBA	DFN2510-10	plastic extremely thin small outline package; no leads; 10 terminals; body 1 × 2.5 × 0.5 mm	SOT1165-1
IP4283CZ10-TBR	DFN2510A-10	plastic extremely thin small outline package; no leads; 10 terminals; body 1 × 2.5 × 0.5 mm	SOT1176-1
IP4283CZ10-TT	TSSOP10	plastic thin shrink small outline package; 10 leads; body width 3 mm	SOT552-1

4. Marking

Table 3. Marking codes

Type number	Marking code
IP4283CZ10-TBA	83
IP4283CZ10-TBR	83
IP4283CZ10-TT	4283

5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_I	input voltage		-0.5	+5.5	V
V_{ESD}	electrostatic discharge voltage	IEC 61000-4-2, level 4 [1]			
		contact discharge	-8	+8	kV
		air discharge	-15	+15	kV
T_{stg}	storage temperature		-55	+125	°C
T_{amb}	ambient temperature		-40	+85	°C

[1] All pins to ground.

6. Characteristics

Table 5. Characteristics

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{BR}	breakdown voltage	$I_{test} = 1\text{ mA}$	6	-	9	V
I_{LR}	reverse leakage current	per TMDS channel; $V = 3\text{ V}$	-	-	1	μA
V_F	forward voltage	$I_{test} = 1\text{ mA}$	-	0.7	-	V
C_{line}	line capacitance	$f = 1\text{ MHz}$; $V_{bias} = 2.5\text{ V}$	[1]	-	0.6	pF
ΔC_{line}	line capacitance difference	$f = 1\text{ MHz}$; $V_{bias} = 2.5\text{ V}$	[1]	-	0.05	pF
$C_{line(mutual)}$	mutual line capacitance	$f = 1\text{ MHz}$; $V_{bias} = 2.5\text{ V}$	[1][2]	-	0.07	pF
r_{dyn}	dynamic resistance	surge [3]				
		positive transient	-	0.8	-	Ω
		negative transient	-	0.85	-	Ω
V_{CL}	clamping voltage	positive transient; $I_{PP} = 3.8\text{ A}$	[3]	-	9.5	V
		negative transient; $I_{PP} = -2.8\text{ A}$	[3]	-	-3.2	V

[1] This parameter is guaranteed by design.

[2] Between signal pin and pin n.c.

[3] According to IEC 61000-4-5 (8/20 μs).

7. Application information

The devices are designed to provide high-level ESD protection for high-speed serial data buses such as HDMI, DisplayPort, eSATA and LVDS data lines.

When designing the Printed-Circuit Board (PCB), give careful consideration to impedance matching, and signal coupling.

Basic application diagrams for the ESD protection of an HDMI interface are shown in [Figure 1](#) and [2](#).

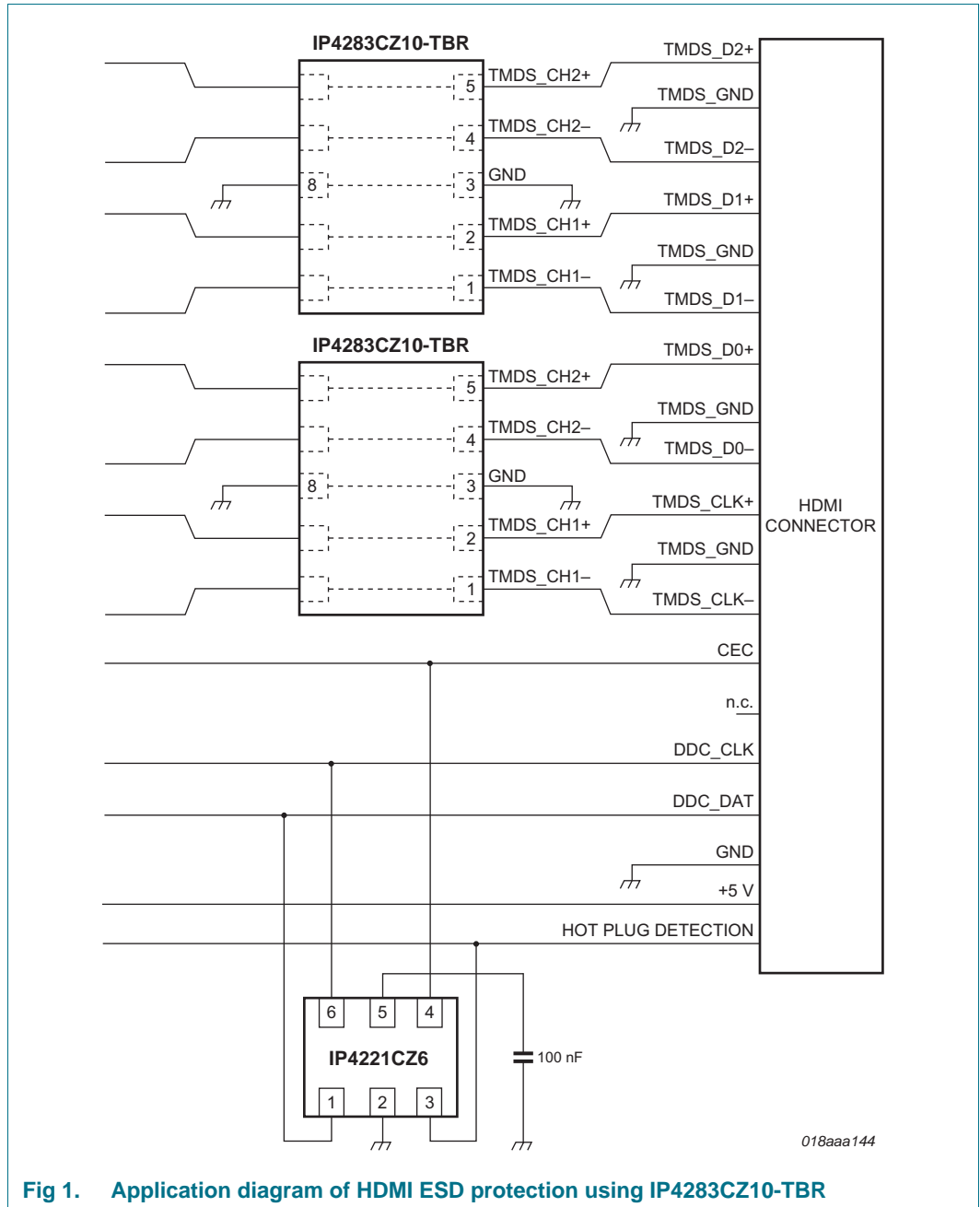


Fig 1. Application diagram of HDMI ESD protection using IP4283CZ10-TBR

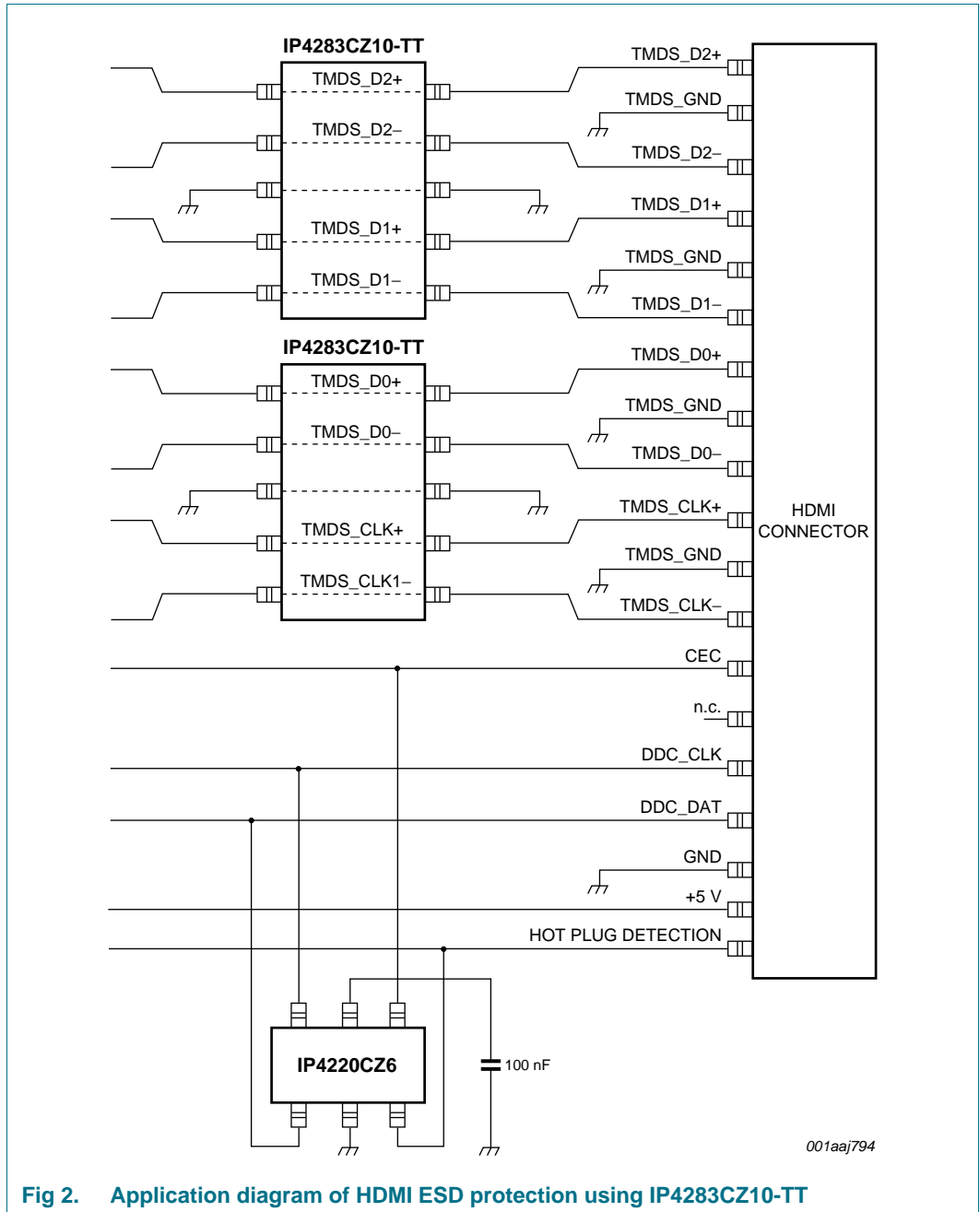
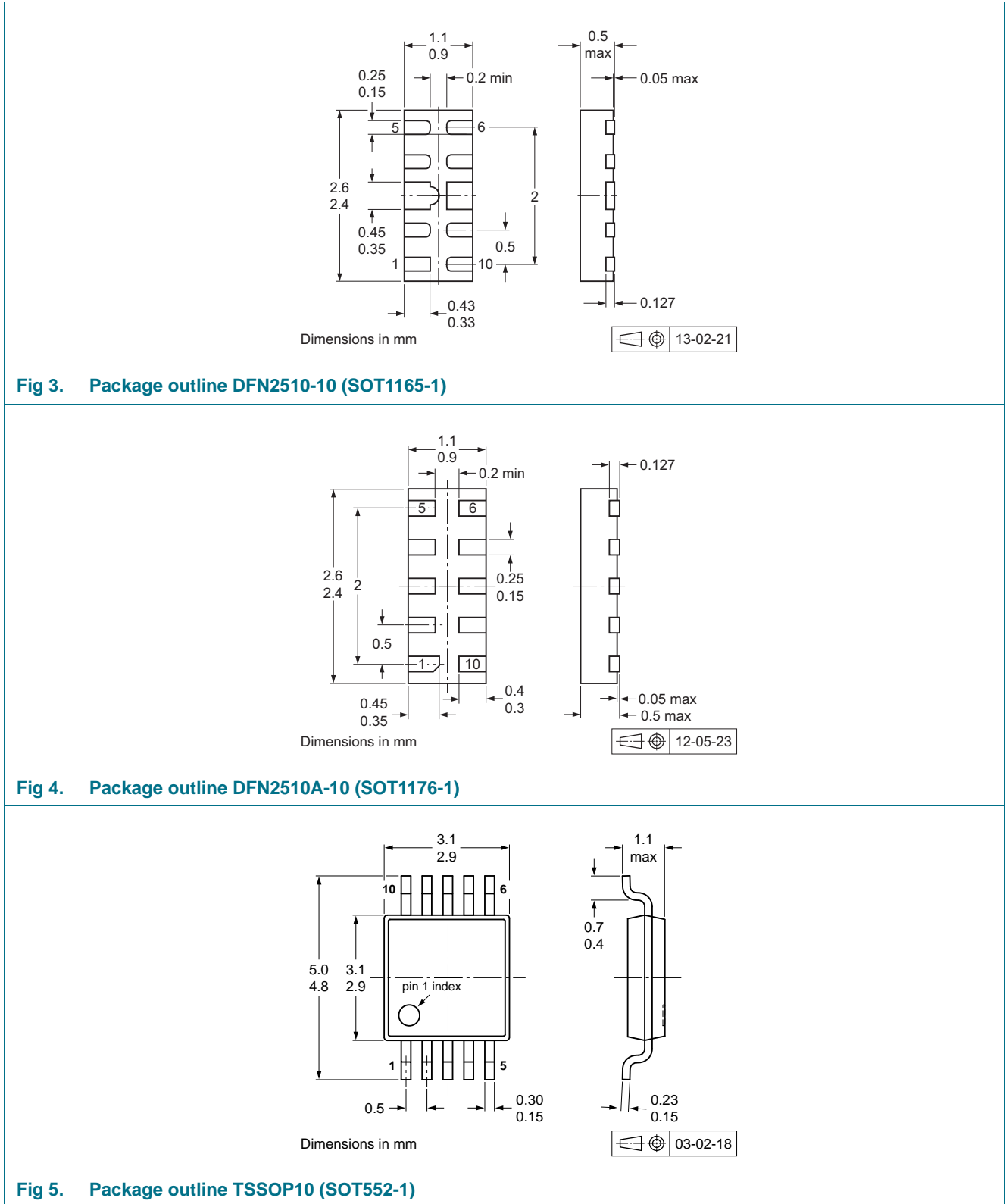


Fig 2. Application diagram of HDMI ESD protection using IP4283CZ10-TT

8. Package outline



9. Soldering

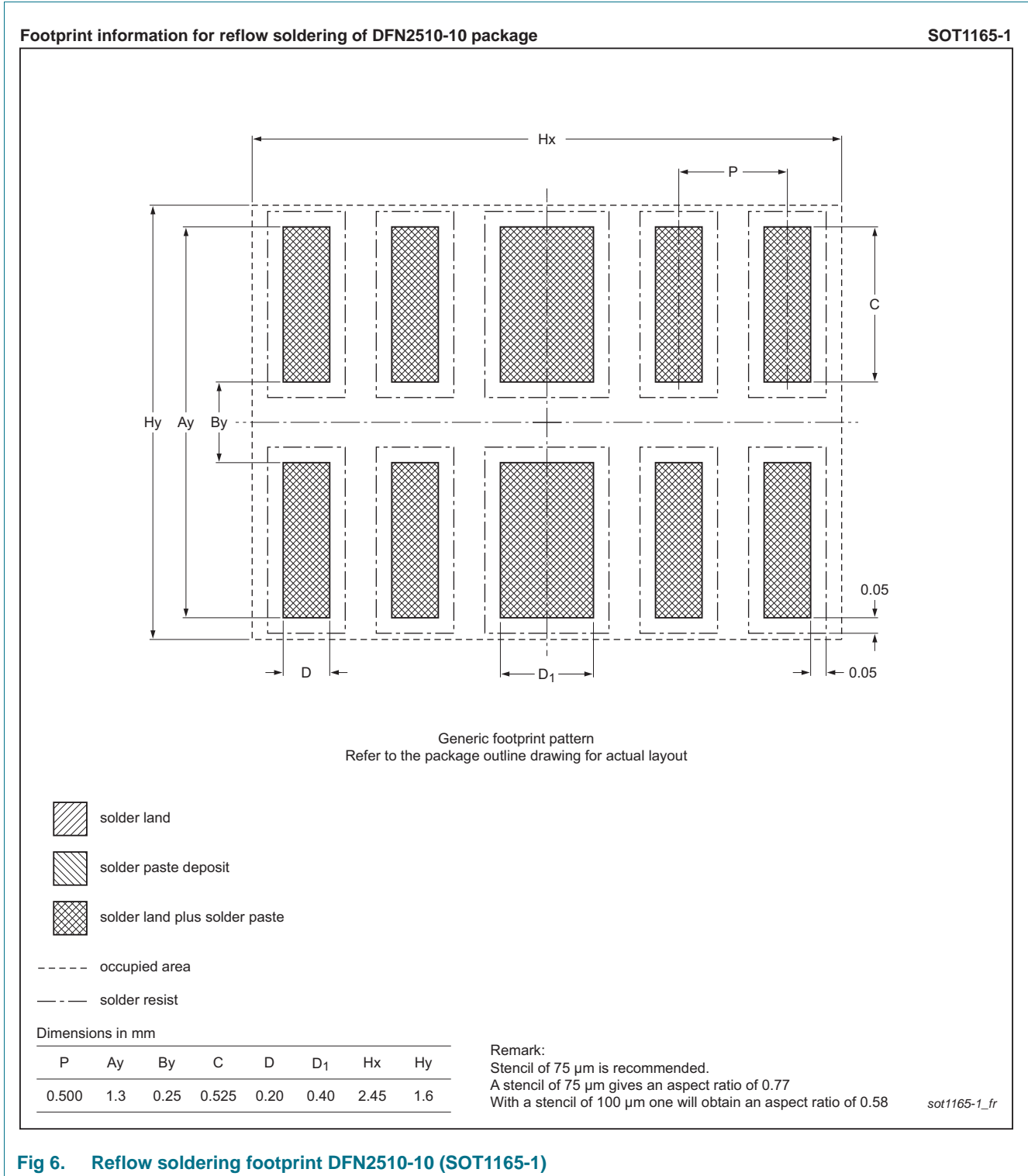


Fig 6. Reflow soldering footprint DFN2510-10 (SOT1165-1)

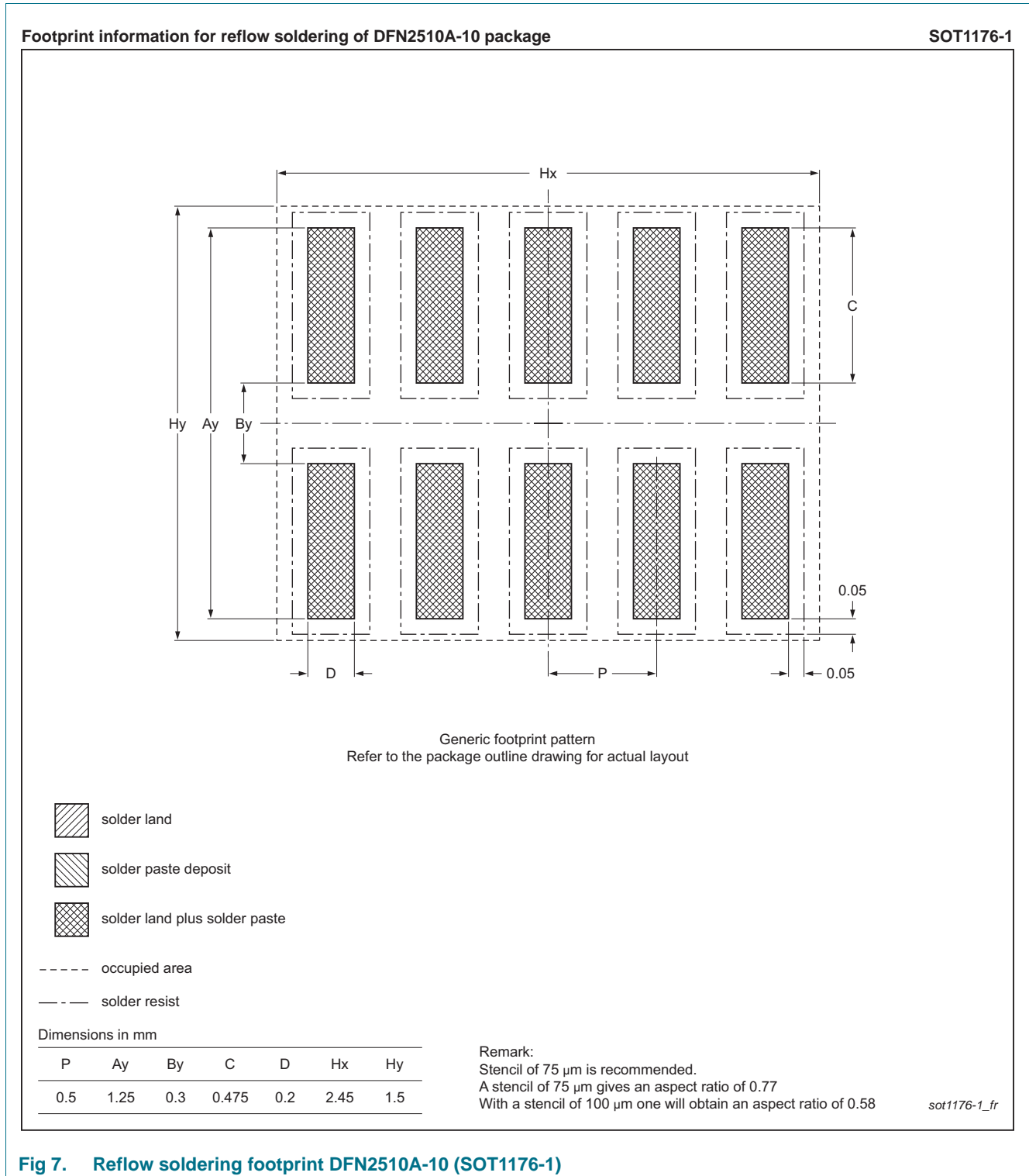


Fig 7. Reflow soldering footprint DFN2510A-10 (SOT1176-1)

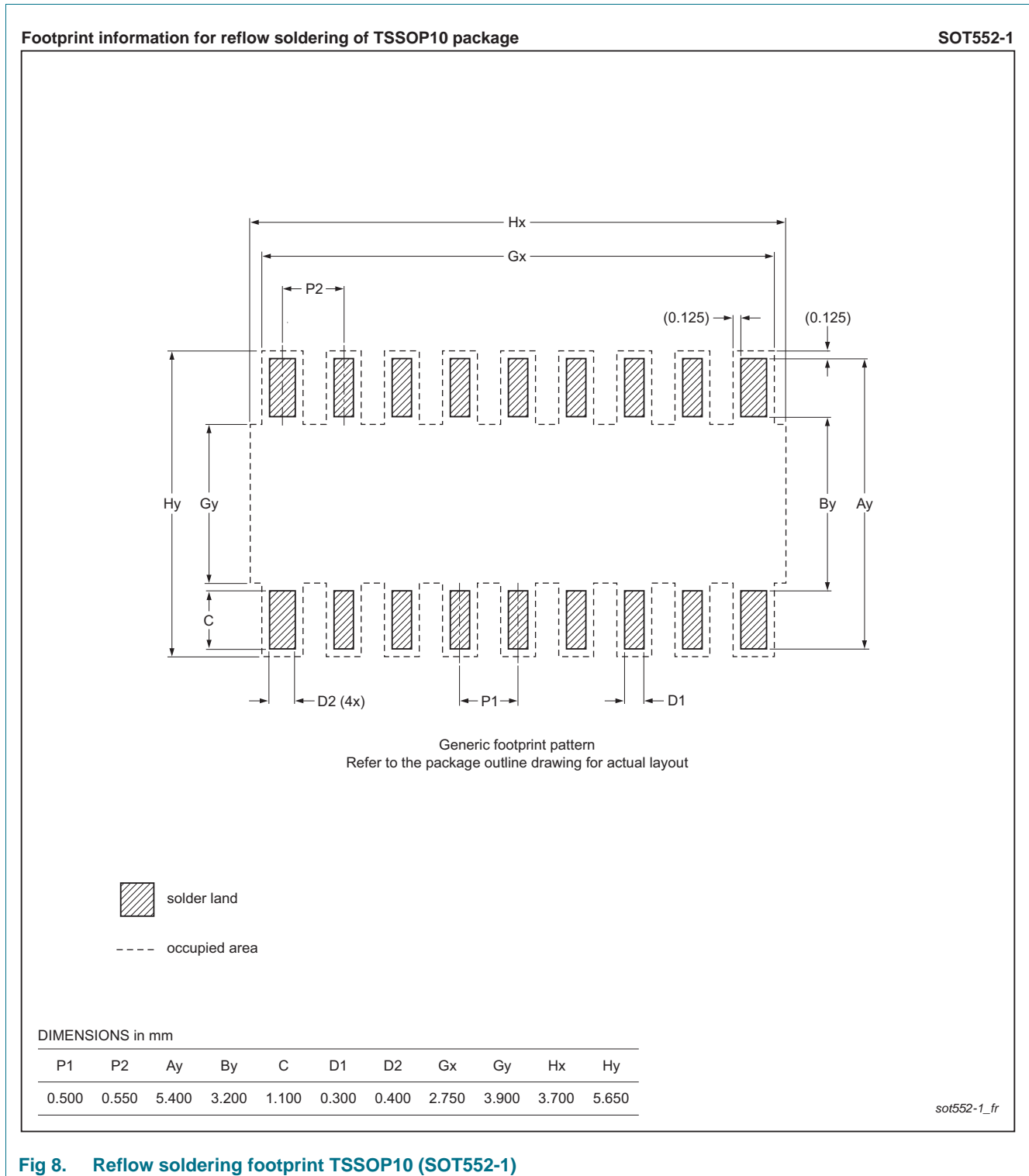


Fig 8. Reflow soldering footprint TSSOP10 (SOT552-1)

10. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
IP4283CZ10_SER v.4	20130408	Product data sheet	-	IP4283CZ10_SER v.3
Modifications:	<ul style="list-style-type: none"> • Section 1.1 “General description”: updated • Section 1.2 “Features and benefits”: updated • Section 2 “Pinning information”: updated • Section 3 “Ordering information”: updated • Table 5 “Characteristics”: updated; r_{dyn} value corrected • Section 8 “Package outline”: drawings replaced with minimized package outline drawings • Section 9 “Soldering”: updated • Section 11 “Legal information”: updated 			
IP4283CZ10_SER v.3	20110624	Product data sheet	-	IP4283CZ10_SER v.2
IP4283CZ10_SER v.2	20100827	Product data sheet	-	IP4283CZ10 v.1
IP4283CZ10 v.1	20090507	Product data sheet	-	-

11. Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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